

Reliability Monitoring Results

Quarters: Q1/2023 to Q4/2023

Based on structural similarity

Supplier		User Part Number				
Nexperia B.V.		74LVC1G38GV				
Part Description: Single 2-input NAND gate; open-drain						
Function Family: LVC Process family: Sub micron Package family: TSOP						
JESD47 Test	Test Conditions	Duration	# Lots	# Quantity	# Rejects	
# 1 TEST Pre- and Post-Stress Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below	
# 2 PC Preconditioning	JESD22-A113 MSL 1	N/A	170	13731	0	
# 5a HTOL EFR High Temperature Operating Life Extrinsic	JESD22-A108 Tj = 150°C V _{CCMAX} ≤ V ≤ 1.2*V _{CCMAX}	48 hours or 168 hours	390	58005	0	
# 5b HTOL IFR High Temperature Operating Life Intrinsic	JESD22-A108 Tj = 150°C V _{CCMAX} ≤ V ≤ 1.2*V _{CCMAX}	≥500 hours	165	12325	0	
# 7 TC Temperature Cycling	JESD22-A104 -65 °C to 150°C	≥500 cycles	81	6471	0	
# 9 uHAST / HAST unbiased or biased High Accelerated Stress Test	JESD22-A101 Tamb = 130 °C, RH = 85%, V = V _{CCMAX}	96 hours	91	7260	0	

Calculation of PPM, FIT and MTTF

Test considered for PPM calculation: High Temperature Operating LifeTest Extrinsic (HTOL EFR, Test # 5a above)

Test considered for FIT and MTTF calculations: High Temperature Operating LifeTest Intrinsic (HTOL IFR, Test # 5b above)

Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Product Family	Package Family	Quantity	Rejects	Extrinsic Failure Rate (PPM)	Intrinsic Failure Rate (FIT)	MTTF (hrs)
LVC	TSOP	12325	0	16	0.4	2.99 E+09